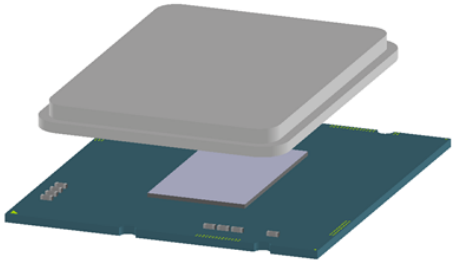
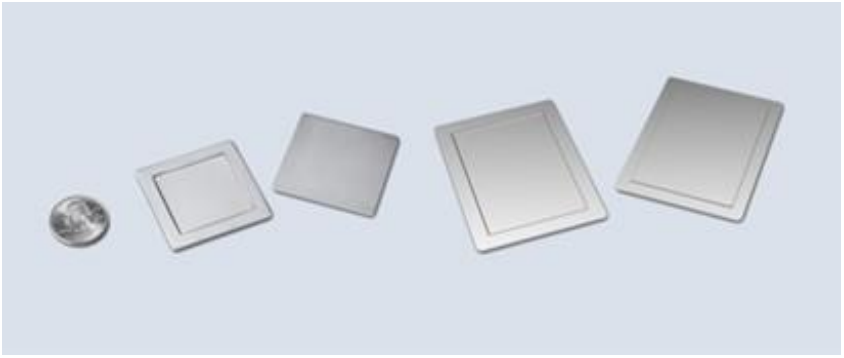
Heat Spreader

Introduction

A heat spreader is high thermal conductive metallic materials for efficient heat dissipation from an IC chip in a semiconductor package.
SHINKO manufactures various types of heat spreaders by using excellent stamping and surface finish treatment technologies. These spreaders are used in CPUs for desktop personal computers and servers.

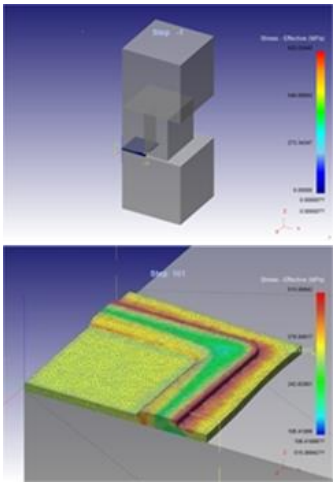




Features

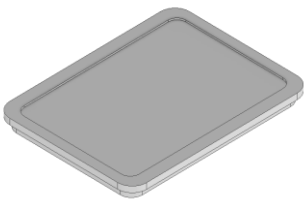
- Mass-production technology for Transfer stamping
- Products with more complicated shapes can be produced by combining stamping and machining
- Lead time reduction of stamping tools by using simulation
- Consistent process from stamping die tool design and manufacturing, heat spreader stamping and machining to surface treatment
- Advanced surface treatment for superior corrosion resistance and ease for package assembly
- Specifications
  - Material : Cu (C1020, C1100)
  - Surface Treatment : Electrolytic Ni Plating
    or Electrolytic Ni/Selective Au Plating
  - Heat spreader Size : Outer Length 10 ~ 100 mm,
    : Thickness 1.0 ~ 4.5 mm

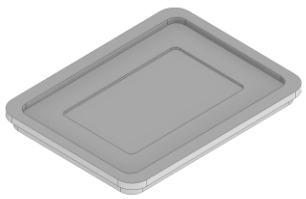
Simulation of Stamping Tools
(Stress Analysis)

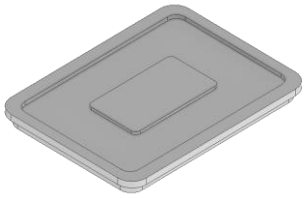


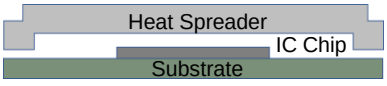
- Support various sizes and shapes for meeting your chip size and location

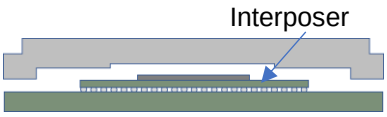
Standard Shape	Multi-step Shape for Interposer	Pedestal Shape for Heterogeneous Integration











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